



# SOT903-1

plastic thermal enhanced low profile quad flat package; no leads; 64 terminals; resin based; body 9 x 9 x 1.6 mm

8 February 2016

Package information

## 1. Package summary

|                                       |  |
|---------------------------------------|--|
| <b>Terminal position code</b>         | Q (quad)   |
| <b>Package type descriptive code</b>  | HLQFN64R   |
| <b>Package type industry code</b>     | HLQFN64R   |
| <b>Package style descriptive code</b> | HLQFN (thermal enhanced low profile quad flatpack; no leads) |
| <b>Package style suffix code</b>      | R (resin based)  |
| <b>Package body material type</b>     | P (plastic)  |
| <b>Mounting method type</b>           | S (surface mount)  |
| <b>Issue date</b>                     | 14-11-2007   |

Table 1. Package summary

| Symbol         | Parameter                      | Min   | Typ | Nom | Max   | Unit |
|----------------|--------------------------------|-------|-----|-----|-------|------|
| D              | package length                 | 8.9   | -   | 9   | 9.1   | mm   |
| E              | package width                  | 8.9   | -   | 9   | 9.1   | mm   |
| A              | seated height                  | [tbd] | -   | 1.6 | 1.7   | mm   |
| A <sub>2</sub> | package height                 | [tbd] | -   | 1.6 | [tbd] | mm   |
| n <sub>2</sub> | actual quantity of termination | -     | -   | 64  | -     |      |



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## 2. Package outline

HLQFN64R; plastic thermal enhanced low profile quad flat package; no leads; 64 terminals; resin based; body 9 x 9 x 1.6 mm

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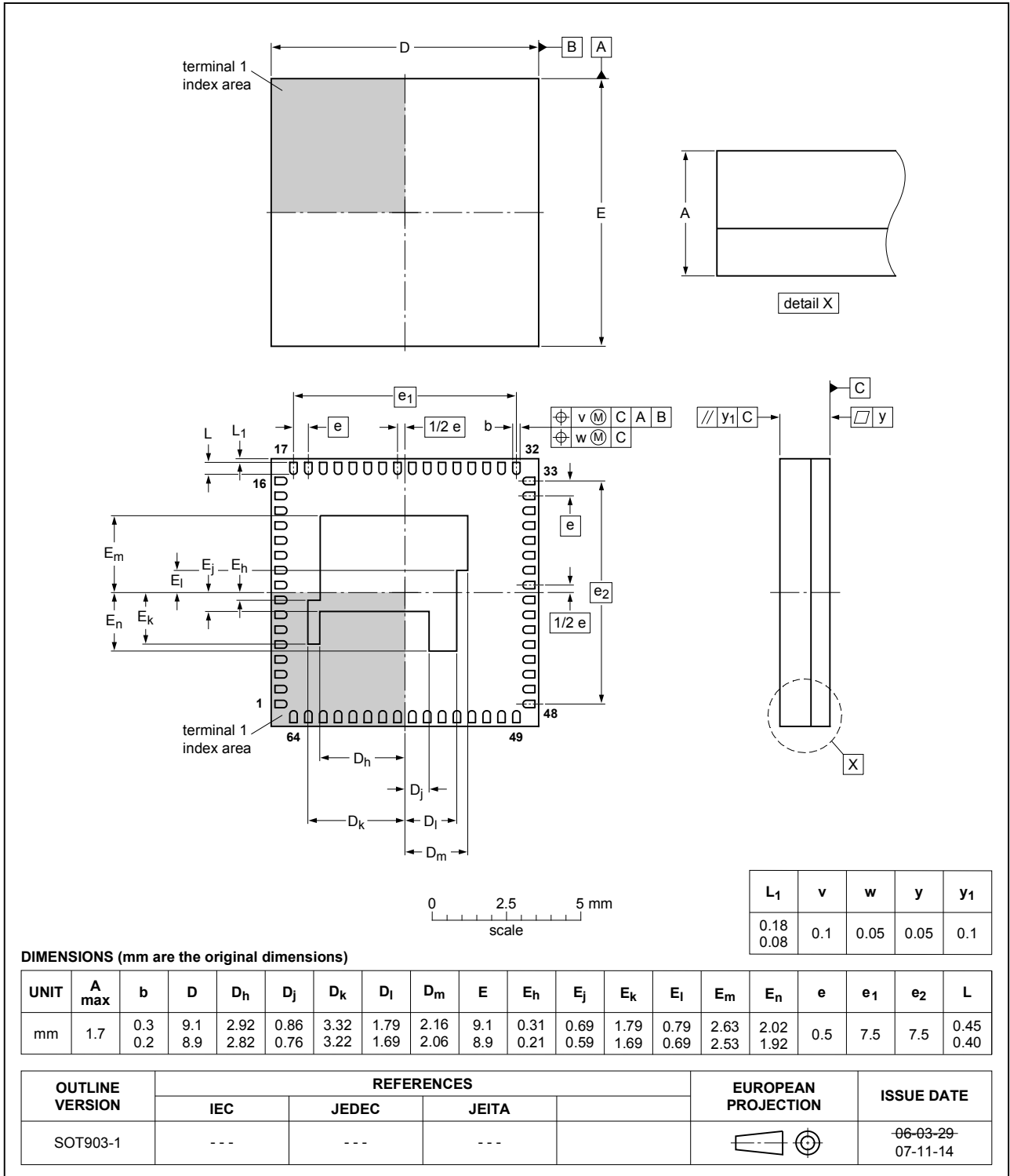
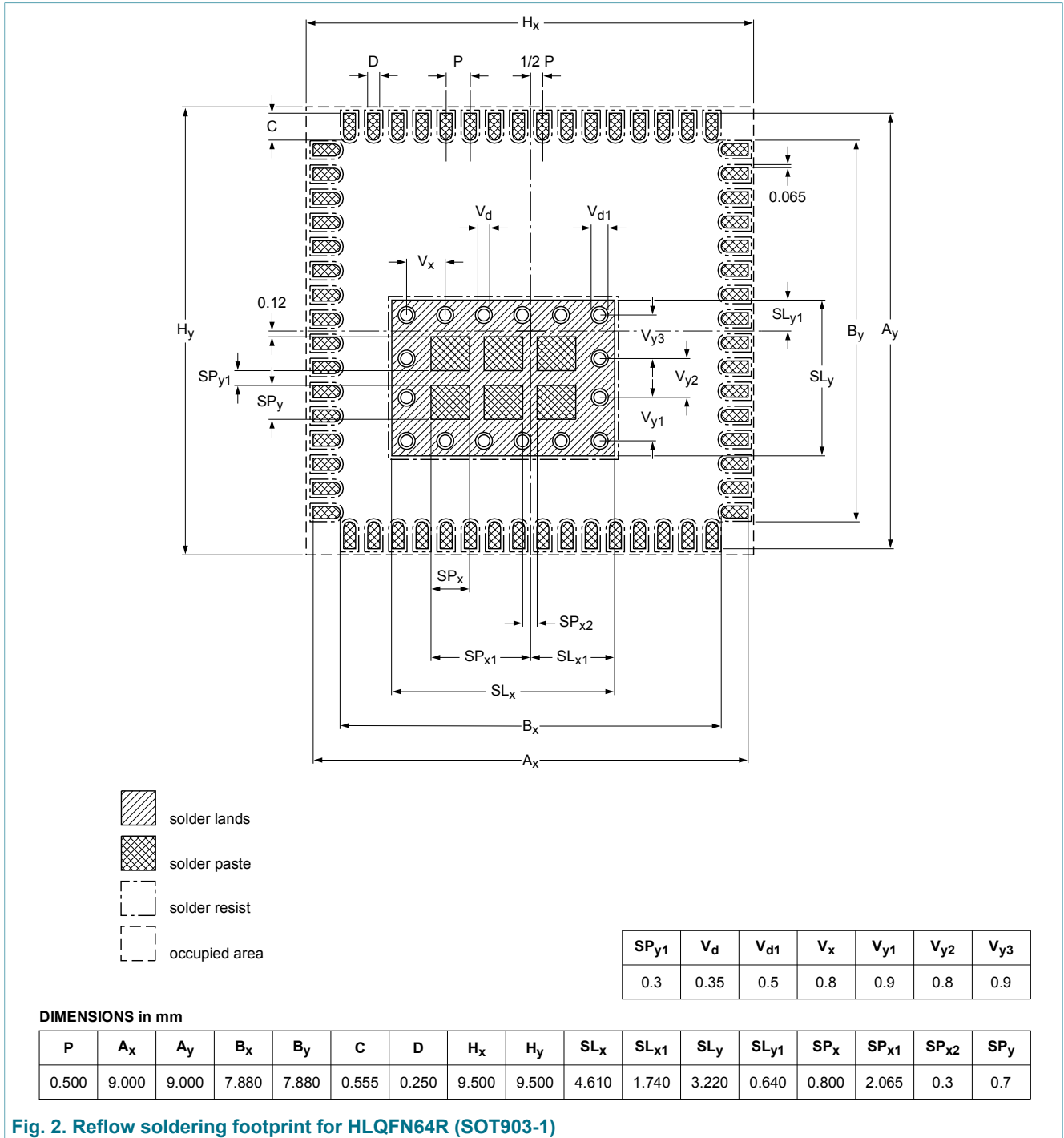


Fig. 1. Package outline HLQFN64R (SOT903-1)

plastic thermal enhanced low profile quad flat package; no leads; 64 terminals; resin based; body 9 x 9 x 1.6 mm

### 3. Soldering



plastic thermal enhanced low profile quad flat  
package; no leads; 64 terminals; resin based;  
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## 4. Legal information

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